

MOSFETs Silicon N-channel MOS (U-MOSIX-H)

TPHR6503PL

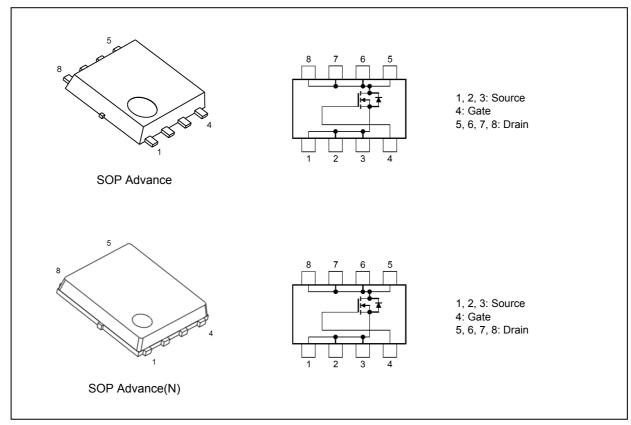
1. Applications

- · High-Efficiency DC-DC Converters
- Switching Voltage Regulators

2. Features

- (1) High-speed switching
- (2) Small gate charge: $Q_{SW} = 30 \text{ nC (typ.)}$
- (3) Small output charge: $Q_{oss} = 81.3 \text{ nC (typ.)}$
- (4) Low drain-source on-resistance: $R_{DS(ON)} = 0.41 \text{ m}\Omega$ (typ.) ($V_{GS} = 10 \text{ V}$)
- (5) Low leakage current: $I_{DSS} = 10 \mu A \text{ (max) (V}_{DS} = 30 \text{ V)}$
- (6) Enhancement mode: $V_{th} = 1.1$ to 2.1 V ($V_{DS} = 10$ V, $I_D = 1.0$ mA)

3. Packaging and Internal Circuit



The package can be selected according to your preference. For details, please contact your TOSHIBA sales representative.

Start of commercial production

Downloaded from Arrow.com.



4. Absolute Maximum Ratings (Note) (Ta = 25 °C unless otherwise specified)

Characteristics	S		Symbol	Rating	Unit
Drain-source voltage			V_{DSS}	30	V
Gate-source voltage		(Note 1)	V_{GSS}	±20	
Drain current (DC)	(T _c = 25 °C)	(Note 2)	I _D	150	Α
Drain current (DC)	(Silicon limit)	(Note 2), (Note 3)	I_D	393	Α
Drain current (pulsed)	(t = 100 μs)	(Note 2)	I_{DP}	500	Α
Power dissipation	(T _c = 25 °C)		P_D	170	W
Power dissipation		(Note 4)	P_{D}	3.0	W
Power dissipation		(Note 5)	P_D	0.96	W
Single-pulse avalanche energy		(Note 6)	E _{AS}	374	mJ
Single-pulse avalanche current		(Note 6)	I _{AS}	120	Α
Channel temperature			T _{ch}	175	ů
Storage temperature	-		T _{stg}	-55 to 175	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

5. Thermal Characteristics

Characteristics			Symbol	Max	Unit
Channel-to-case thermal resistance	(T _c = 25 °C)		R _{th(ch-c)}	0.88	°C/W
Channel-to-ambient thermal resistance	(T _a = 25 °C)	(Note 4)	R _{th(ch-a)}	50	
Channel-to-ambient thermal resistance	(T _a = 25 °C)	(Note 5)	R _{th(ch-a)}	156	

Note 1: +20V /-16V ensured at DC condition.

-20V ensured at pulse condition(duty 5%).

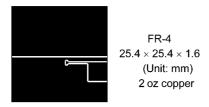
Note 2: Ensure that the channel temperature does not exceed 175 °C.

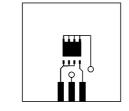
Note 3: Limited by silicon chip capability. Package limit is 150 A.

Note 4: Device mounted on a glass-epoxy board (a), Figure 5.1

Note 5: Device mounted on a glass-epoxy board (b), Figure 5.2

Note 6: V_{DD} = 24 V, T_{ch} = 25 °C (initial), L = 0.02 mH, I_{AS} = 120 A





FR-4 25.4 × 25.4 × 1.6 (Unit: mm) 2 oz copper

Fig. 5.1 Device Mounted on a Glass-Epoxy Board (a)

Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.



6. Electrical Characteristics

6.1. Static Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I _{GSS}	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±0.1	μА
Drain cut-off current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V	_	_	10	
Drain-source breakdown voltage	V _{(BR)DSS}	I _D = 10 mA, V _{GS} = 0 V	30		_	٧
	V _{(BR)DSX}	I _D = 10 mA, V _{GS} = -20 V	15	_	_	
Gate threshold voltage	V_{th}	V _{DS} = 10 V, I _D = 1.0 mA	1.1	_	2.1	
Drain-source on-resistance	R _{DS(ON)}	$V_{GS} = 4.5 \text{ V}, I_D = 50 \text{ A}$	_	0.6	0.89	mΩ
		V _{GS} = 10 V, I _D = 50 A	_	0.41	0.65	

6.2. Dynamic Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C _{iss}	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz	_	7700	10000	pF
Reverse transfer capacitance	C _{rss}		_	220	_	
Output capacitance	C _{oss}		_	2720	_	
Gate resistance	r _g	_	_	0.6	1.1	Ω
Switching time (rise time)	t _r	See Fig. 6.2.1	_	12	_	ns
Switching time (turn-on time)	t _{on}		_	36	_	
Switching time (fall time)	t _f		_	10	_	
Switching time (turn-off time)	t _{off}		_	100	_	

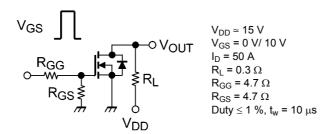


Fig. 6.2.1 Switching Time Test Circuit

6.3. Gate Charge Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus	Q_g	$V_{DD} \approx 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 50 \text{ A}$	_	110	1	nC
gate-drain)		$V_{DD} \approx 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 50 \text{ A}$	_	52		
Gate-source charge 1	Q _{gs1}	$V_{DD} \approx 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 50 \text{ A}$	_	24		
Gate-drain charge	Q_{gd}		_	16		
Gate switch charge	Q_{SW}		_	30		
Output charge	Q _{oss}	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz	_	81.3	_	

6.4. Source-Drain Characteristics (T_a = 25 °C unless otherwise specified)

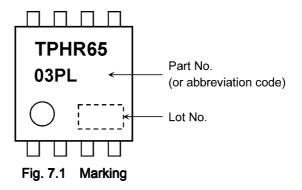
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (pulsed) (Note 7)	I _{DRP} (t = 100 μs)	_		-	500	Α
Diode forward voltage	V _{DSF}	I _{DR} = 150 A, V _{GS} = 0 V		_	-1.2	V
Reverse recovery time		V _R = 15 V, I _{DR} = 37.5 A, V _{GS} =	_	59	_	ns
Reverse recovery charge	Q _{rr}	0 V, -dl _{DR} /dt = 100 A/μs	_	70	_	nC

Note 7: Ensure that the channel temperature does not exceed 175 °C.

2019-10-18



7. Marking





8. Characteristics Curves (Note)

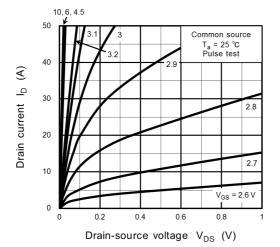


Fig. 8.1 I_D - V_{DS}

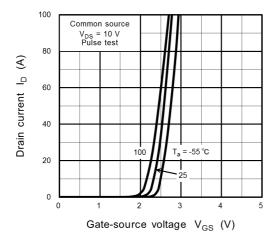


Fig. 8.3 $I_D - V_{GS}$

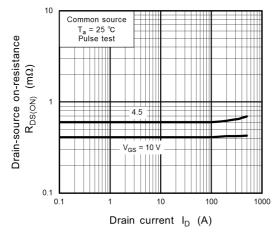


Fig. 8.5 R_{DS(ON)} - I_D

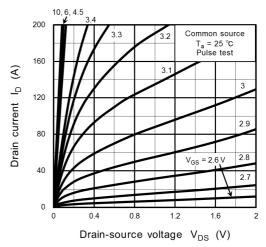


Fig. 8.2 I_D - V_{DS}

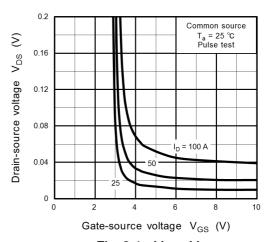


Fig. 8.4 V_{DS} - V_{GS}

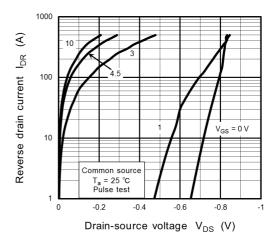


Fig. 8.6 I_{DR} - V_{DS}



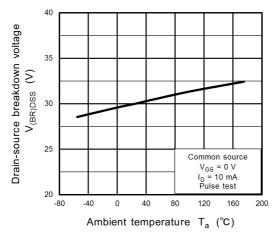


Fig. 8.7 V_{(BR)DSS} - T_a

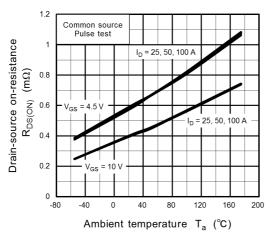


Fig. 8.9 R_{DS(ON)} - T_a

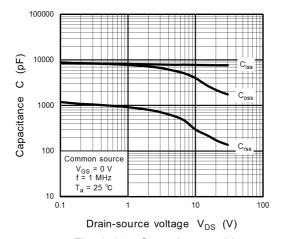


Fig. 8.11 Capacitance - V_{DS}

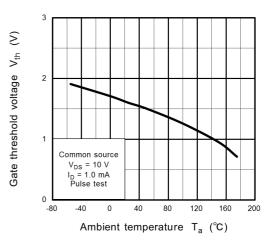


Fig. 8.8 V_{th} - T_a

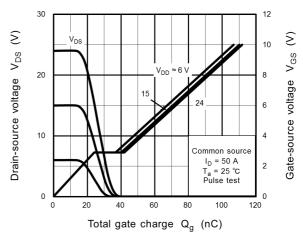


Fig. 8.10 Dynamic Input/Output Characteristics

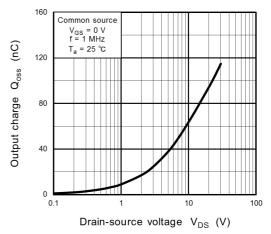


Fig. 8.12 Qoss - VDS



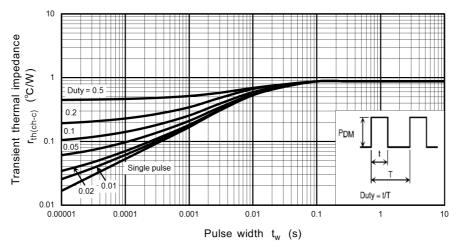


Fig. 8.13 r_{th} - t_w (Guaranteed Maximum)

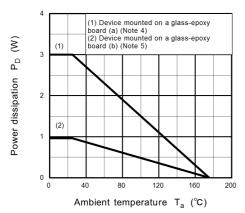


Fig. 8.14 P_D - T_a Guaranteed Maximum

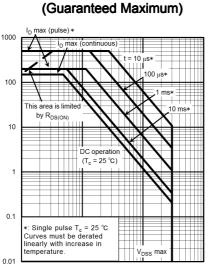
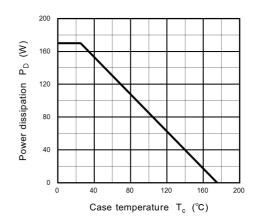


Fig. 8.16 Safe Operating Area (Guaranteed Maximum)

Drain-source voltage V_{DS} (V)



 $\label{eq:Fig. 8.15} \begin{array}{ll} \text{Fig. 8.15} & \text{P}_{\text{D}} \text{-} \text{T}_{\text{C}} \\ \text{(Guaranteed Maximum)} \end{array}$

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

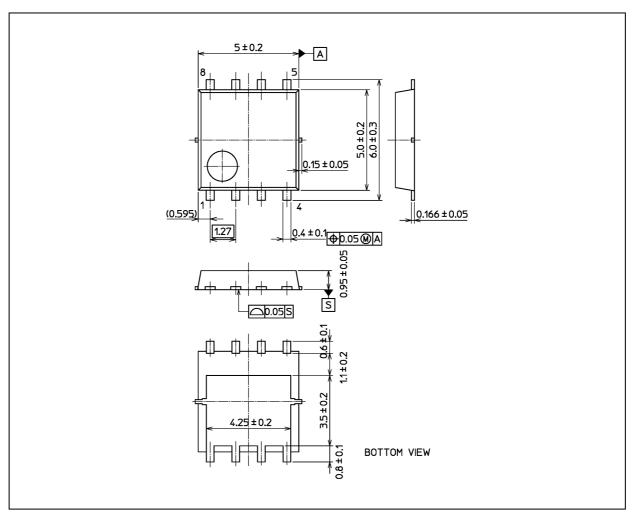
Rev.4.0

Drain current I_D (A)



Package Dimensions

Unit: mm



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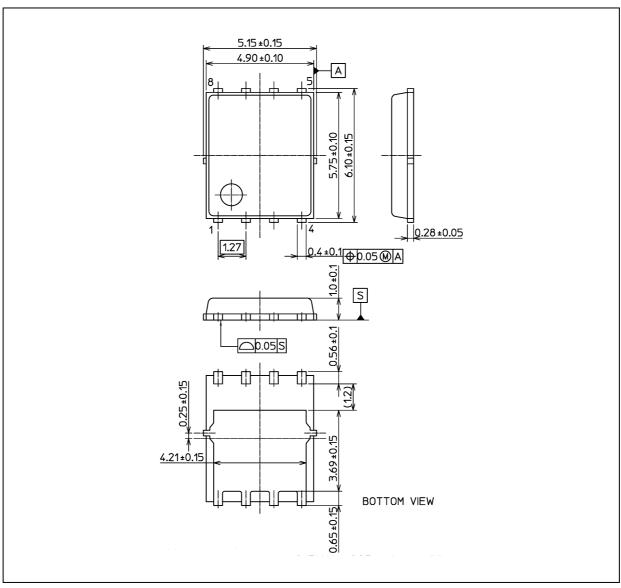
Weight: 0.087 g (typ.)

1	Package Name(s)
TOSHIBA: 2-5Q1S	
Nickname: SOP Advance	



Package Dimensions

Unit: mm



The package can be selected according to your preference. For details, please contact your TOSHIBA sales representative.

Weight: 0.111 g (typ.)

Package Name(s)
TOSHIBA: 2-5W1A
Nickname: SOP Advance(N)



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